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colour inside

Printed board assemblies –
Part 2: Sectional specification – Requirements for surface mount soldered assemblies

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COMMISSION

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PRINTED BOARD ASSEMBLIES –

Part 2: Sectional specification – Requirements for surface mount soldered assemblies

FOREWORD

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International Standard IEC 61191-2 has been prepared by IEC technical committee 91: Electronics assembly technology.

This third edition cancels and replaces the second edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) the requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F;
b) some of the terminology used in the document has been updated;
c) references to IEC standards have been corrected;
d) five termination styles have been added.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1386/CDV	91/1429/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61191 under the general title *Printed board assemblies* can be found in the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

The contents of the corrigendum of September 2019 have been included in this copy.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

PRINTED BOARD ASSEMBLIES –

Part 2: Sectional specification – Requirements for surface mount soldered assemblies

1 Scope

This part of IEC 61191 gives the requirements for surface mount solder connections. The requirements pertain to those assemblies that are totally surface mounted or to the surface mounted portions of those assemblies that include other related technologies (e.g. through-hole, chip mounting, terminal mounting, etc.).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61191-1, *Printed board assemblies – Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies*

IPC-A-610, Acceptability of Electronic Assemblies